

Title (en)  
AN EXTRUDED POROUS SUBSTRATE HAVING INORGANIC BONDS

Title (de)  
EXTRUDIERTES PORÖSES SUBSTRAT MIT ANORGANISCHEN BINDUNGEN

Title (fr)  
SUBSTRAT POREUX EXTRUDÉ COMPRENANT DES LIAISONS INORGANIQUES

Publication  
**EP 2051790 A4 20110504 (EN)**

Application  
**EP 07758485 A 20070314**

Priority  

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Abstract (en)  
[origin: WO2008021587A2] A method is provided for producing a highly porous substrate. More particularly, the present invention enables fibers, such as organic, inorganic, glass, ceramic, polymer, or metal fibers, to be combined with binders and additives, and extruded, to form a porous substrate. Depending on the selection of the constituents used to form an extrudable mixture, the present invention enables substrate porosities of about 60% to about 90%, and enables process advantages at other porosities, as well. The extrudable mixture may use a wide variety of fibers and additives, and is adaptable to a wide variety of operating environments and applications. Additives can be selected that form inorganic bonds between overlapping fibers in the extruded substrate that provide enhanced strength and performance of the porous substrate in a variety of applications, such as, for example, filtration and as a host for catalytic processes, such as catalytic converters.

IPC 8 full level  
**B01D 24/00** (2006.01); **B01D 39/06** (2006.01); **B01D 39/20** (2006.01); **C04B 24/00** (2006.01); **C04B 35/111** (2006.01); **C04B 35/18** (2006.01); **C04B 35/486** (2006.01); **C04B 35/80** (2006.01)

CPC (source: EP KR US)  
**B01D 24/00** (2013.01 - KR); **B01D 39/06** (2013.01 - KR); **B01D 39/20** (2013.01 - KR); **C04B 24/00** (2013.01 - KR); **C04B 35/111** (2013.01 - EP US); **C04B 35/18** (2013.01 - EP US); **C04B 35/486** (2013.01 - EP US); **C04B 35/80** (2013.01 - EP US); **C04B 38/0006** (2013.01 - EP); **C04B 38/0615** (2013.01 - EP US); **B01J 35/56** (2024.01 - EP); **C04B 2111/00793** (2013.01 - EP); **C04B 2111/0081** (2013.01 - EP); **C04B 2235/3418** (2013.01 - EP); **C04B 2235/3463** (2013.01 - EP); **C04B 2235/425** (2013.01 - EP); **C04B 2235/5228** (2013.01 - EP)

C-Set (source: EP)  
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Citation (search report)  

- No further relevant documents disclosed
- See references of WO 2008021587A2

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DOCDB simple family (publication)  
**WO 2008021587 A2 20080221; WO 2008021587 A3 20080828**; AU 2007284302 A1 20080221; AU 2007284302 B2 20120209; CA 2660833 A1 20080221; CN 101505847 A 20090812; CN 101505847 B 20110907; EP 2051790 A2 20090429; EP 2051790 A4 20110504; JP 2010501451 A 20100121; KR 20090057392 A 20090605; MX 2009001851 A 20090415

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